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[illegible]

PATENT NUMBER

## U.S. UTILITY Patent Application

HKM O.I.P.E. SCANNED <u>321</u> Q.A. <u>HT</u>	PATENT DATE
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APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/736864	F	257	737	2811 2345	Chu

APPLICANTS  
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TITLE  
 Interconnection substrate having metal columns covered by a resin film, and manufacturing method thereof

PTO-2040  
 12/89

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<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>	<b>DRAWINGS</b> Sheets Dwg.    Fig. Dwg.    Print Fig.		<b>CLAIMS ALLOWED</b> Total Claims    Print Claim for O.G.	
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.  <input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent. No. _____	_____ (Assistant Examiner)    (Date)		<b>NOTICE OF ALLOWANCE MAILED</b>	
	_____ (Primary Examiner)    (Date)		<b>ISSUE FEE</b> Amount Due    Date Paid	
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner)    (Date)		<b>ISSUE BATCH NUMBER</b>	

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